Low Temp. Lead Free Soldering Kits FOR HEAT SENSITIVE ASSEMBLY



Sn42/Bi58 Solder Kits

Qualitek's low temp. lead free soldering kits are a recommended lead free soldering alternative for heat sensitive assembly that requires a low melting point. The low melting point prevents thermal degradation of the heat sensitive components. Alloys exceed J-STD-006 requirements and all other international standards. Qualitek manufactures soldering materials in the U.S.A. and abroad. Kit items are also sold separately

SOLID CORE WIRE SOLDER SN42/BI58

Packed in 500 gram per box .032" and .048" diameter readily available. Qualitek's Sn42/Bi58 alloy exceed impurity requirements of J-STD-006 and all other relevant international standards.

SOLDER PASTES

888D NO-CLEAN SN42/BI58

Packed in 35 grams/10cc or 100 grams 35cc syringes. Type 3 or 4 Exhibits excellent print definition and long tack life. Minimum post solder residues are non-conductive, noncorrosive and highly insulated. Flux classification ROM1 per JSTD-004.

825HF NO-CLEAN SN42/BI58

250 gram or 500 gram jar. Type 3 or 4. Flux classification ROL0 per JSTD-004.

FLUX PEN LT NO-CLEAN

Formulated for low temp. applications, heat sensitive assembly. Sold as part of the kit in 1/3oz applicator or separately in a box of 25. Marker style Rework Wands are pen like reservoirs for applying flux. The mechanical nature permits a localized, controlled application of flux for rework or adding components. Flux classification ROL1 per J-STD-004.

PASTE FLUX PF 608 NO-CLEAN

Packed in 8gms. 10cc syringes. Unique mixture of high grade synthetic resin and thixotropic agents designed specifically for use with both high and low temperature lead free alloys as well as conventional Sn/Pb alloys. It provides the fluxing activity levels that promote fast wetting action and maximum wetting spread. Flux classification R0L0 per J-STD-004.

TIP TINNER SN42/BI58

Packed in 1 oz. can. Unique Tip Tinner is a mixture of solder powder and thermally stable, oxide-reducing compounds. Tip Tinner provides better cleaning and re-tinning of highly oxidized soldering iron tips than wet sponge or rosin-cored wire.



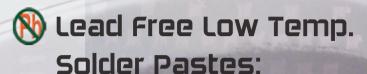
www.qualitek.com

U.S.A. - Singapore - Europe



DELTA SOLDER

PRINT BRICKS EVERY TIME



DSP 825HF No-Clean Solder Paste Stencil Printing

Alloy: Sn42/Bi58

- ROL0 Flux classification
- Halogen -Free
- · Excellent wetting and coalescence
- · Enhanced fine pitch printing

DSP 863 No-Clean Solder Paste Stencil Printing

Alloy: Sn42/Bi58

- ROL0 Flux classification
- Halogen-Free
- Low melting temperature alloy
- · Medium-soft non-cracking residue

DSP 888D No-Clean Solder Paste Syringe Dispensing

Alloy: Sn42/Bi58

- ROL0 Flux classification
- · Easily dispensed
- · Hard, non-conductive residues
- · Designed specifically for low temperature applications

Particle Size Chart

Mesh Size	Microns Size	Particle Type
-200+325	75-45	2
-325+500	45-25	3
-400+635	38-20	4
-500	25-15	5
-635	15-5	6

Paste Packaging Options

Type Designation	Description	Net Weight
Jar	3 - 4 oz., Jar	250 - 500 grams
Semco & Pyle Cartridges	6 oz., Cartridge 12 oz., Cartridge	700 grams 1400 grams
Syringe	10cc., Syringe 30cc., Syringe	35 grams 100 grams

DSP 798LF Water-Soluble Solder Paste Stencil Printing

Alloy: Sn42/Bi58

- ORH1 Flux classification
- Enhanced activity for a broad range of applications
- Excellent printing characteristics
- · Easy removal of residue

DSP 718D Water-Soluble Solder Paste Syringe Dispensing

Alloy: Sn42/Bi58

- ORH1 Flux classification
- · Easily dispensed
- · Yields bright, shiny joints
- · Designed specifically for lead-free applications





- U.S.A. - Europe - China - Singapore - Philippines -